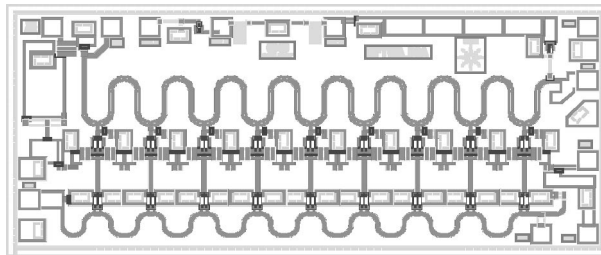


Agilent AMMC-5024

30 KHz – 40 GHz

Traveling Wave Amplifier

Data Sheet



Chip Size: 2350 x 1050 μm (92.5 x 41.3 mils)
 Chip Size Tolerance: $\pm 10 \mu\text{m}$ (± 0.4 mils)
 Chip Thickness: 100 $\pm 10 \mu\text{m}$ (4 ± 0.4 mils)
 Pad Dimensions: 80 x 80 μm (2.95 x 0.4 mils)

Features

- Wide frequency range: 30 KHz – 40 GHz
- High gain: 16 dB
- Gain flatness: ± 0.75 dB
- Return loss: Input: 13 dB, Output: 13 dB
- Medium power: P-1dB = 22.5 dBm at 22 GHz
- Low noise figure: 4.6 dB at 26 GHz

Applications

- Communication systems
- Microwave instrumentation
- Optical systems
- Broadband applications requiring flat gain and group delay with excellent input and output port matches over the 30 KHz and 40 GHz frequency range

Description

Agilent's AMMC-5024 is a broadband PHEMT GaAs MMIC TWA designed for medium output power and high gain over the full 30 KHz to 40 GHz frequency range. The design employs a 9-stage, cascade-connected FET structure to ensure flat gain and power as well as uniform group delay. E-beam lithography is used to produce uniform gate lengths of 0.15 μm and MBE technology assures precise semiconductor layer control.

Absolute Maximum Ratings^[1]

| Symbol | Parameters/Conditions | Units | Min. | Max. |
|-----------|---------------------------------|--------------------|------|------|
| V_{dd} | Positive Drain Voltage | V | | 10 |
| I_{dd} | Total Drain Current | mA | | 340 |
| V_{g1} | First Gate Voltage | V | -9.5 | 0 |
| I_{g1} | First Gate Current | mA | -38 | +1 |
| V_{g2} | Second Gate Voltage | V | -3.5 | +4 |
| I_{g2} | Second Gate Current | mA | -20 | |
| P_{in} | CW Input Power | dBm | | 17 |
| T_{ch} | Operating Channel Temperature | $^{\circ}\text{C}$ | | +150 |
| T_b | Operating Backside Temperature | $^{\circ}\text{C}$ | -55 | |
| T_{stg} | Storage Temperature | $^{\circ}\text{C}$ | -65 | +165 |
| T_{max} | Max. Assembly Temp (60 sec max) | $^{\circ}\text{C}$ | | +300 |

Notes:

1. Absolute maximum ratings for continuous operation unless otherwise noted.



AMMC-5024 DC Specifications/Physical Properties^[1]

| Symbol | Parameters and Test Conditions | Units | Min. | Typ. | Max. |
|-----------------------------|---|---------------------------|------|------|------|
| I_{dss} | Saturated Drain Current ($V_{dd}=7\text{ V}$, $V_{g1}=0\text{ V}$, $V_{g2}=\text{open circuit}$) | mA | 250 | 304 | 350 |
| V_p | First Gate Pinch-off Voltage ($V_{dd}=7\text{ V}$, $I_{dd}=30\text{ mA}$, $V_{g2}=\text{open circuit}$) | V | | -8.2 | |
| V_{g2} | Second Gate Self-bias Voltage ($V_{dd}=7\text{ V}$, $I_{dd}=200\text{ mA}$, $V_{g2}=\text{open circuit}$) | V | | 2.75 | |
| I_{dsmin} (V_{g1}) | First Gate Minimum Drain Current ($V_{dd}=7\text{ V}$, $V_{g1}=-7\text{ V}$, $V_{g2}=\text{open circuit}$) | mA | | 47 | 68 |
| I_{dsmin} (V_{g2}) | Second Gate Minimum Drain Current ($V_{dd}=7\text{ V}$, $V_{g1}=0\text{ V}$, $V_{g2}=-3.5\text{ V}$) | mA | | 105 | 128 |
| θ_{ch-b} | Thermal Resistance ^[2] (Backside temperature, $T_b = 25^\circ\text{C}$) | $^\circ\text{C}/\text{W}$ | | 52 | |

RF Specifications for High Power Applications^[3,4] ($V_{dd}=7\text{ V}$, $I_{dd}(0)=200\text{ mA}$, $Z_{in}=Z_o=50\Omega$)

| Symbol | Parameters and Test Conditions | Units | Min. | Typ. | Max. |
|--------------------|---|--|------|------------|-----------|
| $ S_{21} ^2$ | Small-signal Gain | dB | 14 | 16 | 18 |
| $\Delta S_{21} ^2$ | Small-signal Gain Flatness | dB | | ± 0.75 | ± 1.5 |
| RL_{in} | Input Return Loss | dB | 12 | 16.9 | |
| RL_{out} | Output Return Loss | dB | 10 | 16.8 | |
| $ S_{12} ^2$ | Isolation | dB | 26 | 28 | |
| P_{-1dB} | Output Power @ 1 dB Gain Compression | $f = 22\text{ GHz}$ dBm | 21 | 22.5 | |
| P_{sat} | Saturated Output Power | $f = 22\text{ GHz}$ dBm | 23 | 24.5 | |
| OIP3 | Output 3 rd Order Intercept Point, $Rf_{in1} = Rf_{in2} = 2\text{ dBm}$, $f = 22\text{ GHz}$, $\Delta f = 2\text{ MHz}$ | dBm | 27 | 30 | |
| NF | Noise Figure ($V_{ds} = 3\text{ V}$, $I_{ds} = 140\text{ mA}$) | $f = 26\text{ GHz}$ $f = 40\text{ GHz}$ dB | | 4.6 7.2 | 6.5 9 |

RF Specifications for High Gain and Low Power Applications^[3,4] ($V_{dd}=4\text{ V}$, $I_{dd}(0)=160\text{ mA}$, $Z_{in}=Z_o=50\Omega$)

| Symbol | Parameters and Test Conditions | Units | Min. | Typ. | Max. |
|--------------------|---|--|------|------------|------|
| $ S_{21} ^2$ | Small-signal Gain | dB | | 17.5 | |
| $\Delta S_{21} ^2$ | Small-signal Gain Flatness | dB | | ± 1.5 | |
| RL_{in} | Minimum Input Return Loss | dB | | 13 | |
| RL_{out} | Minimum Output Return Loss | dB | | 13 | |
| $ S_{12} ^2$ | Isolation | dB | | 30 | |
| P_{-1dB} | Output Power @ 1 dB Gain Compression | $f = 22\text{ GHz}$ dBm | | 17.3 | |
| P_{sat} | Saturated Output Power | $f = 22\text{ GHz}$ dBm | | 20.5 | |
| OIP3 | Output 3 rd Order Intercept Point, $Rf_{in1} = Rf_{in2} = 2\text{ dBm}$, $f = 22\text{ GHz}$, $\Delta f = 2\text{ MHz}$ | dBm | | 22.5 | |
| NF | Noise Figure | $f = 26\text{ GHz}$ $f = 40\text{ GHz}$ dB | | 3.7 5.5 | |

Notes:

1. Backside temperature $T_b = 25^\circ\text{C}$ unless otherwise noted.
2. Channel-to-backside Thermal Resistance (θ_{ch-b}) = $61^\circ\text{C}/\text{W}$ at $T_{channel} (T_c) = 150^\circ\text{C}$ as measured using the liquid crystal method. Thermal Resistance at backside temperature (T_b) = 25°C calculated from measured data.
3. Data measured in wafer form, $T_{chuck} = 25^\circ\text{C}$
4. 100% on-wafer RF test is done at frequency = 2, 10, 20, 30 and 40 GHz, except as noted.

AMMC-5024 Typical Performance ($T_{\text{chuck}} = 25^{\circ}\text{C}$, $V_{\text{dd}} = 7\text{V}$, $I_{\text{dd}} = 200\text{ mA}$, $V_{\text{g2}} = \text{Open}$, $Z_0 = 50\Omega$)

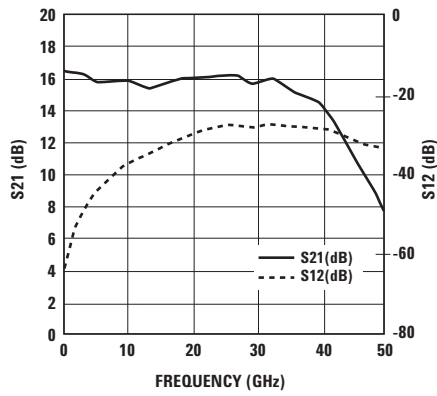


Figure 1. Gain and Reverse Isolation.

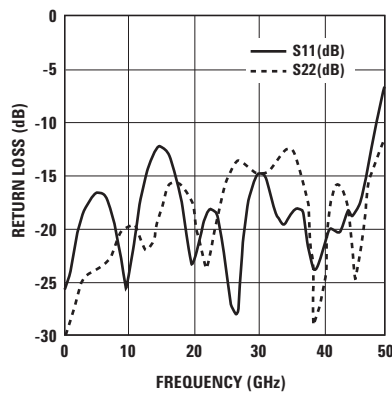


Figure 2. Return Loss (Input and Output).

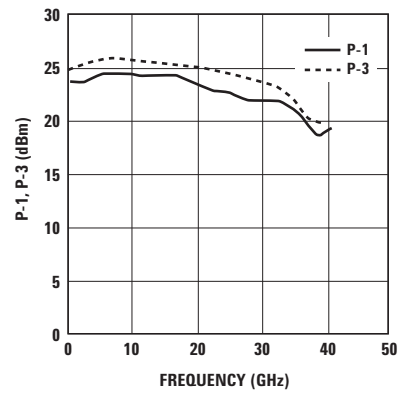


Figure 3. Output Power (P-1 and P-3).

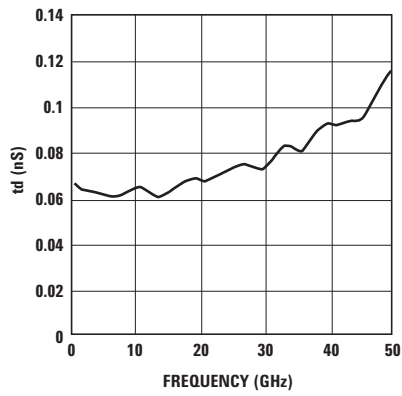


Figure 4. Group Delay.

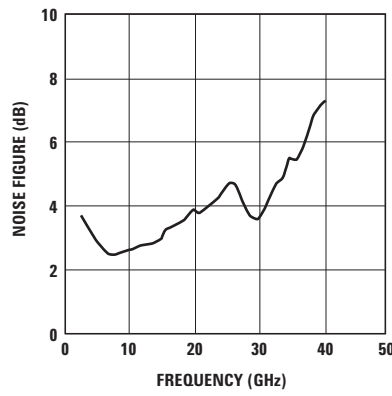


Figure 5. Noise Figure.

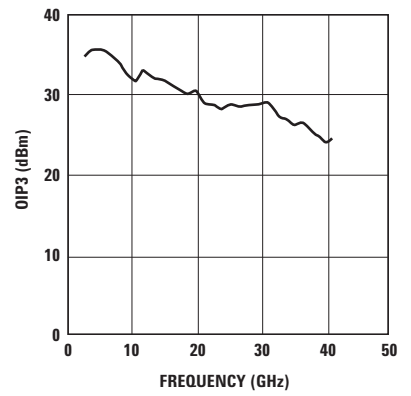


Figure 6. Output IP3.

AMMC-5024 Typical Performance ($T_{\text{chuck}} = 25^{\circ}\text{C}$, $V_{\text{dd}} = 4\text{V}$, $I_{\text{dd}} = 160\text{ mA}$, $V_{\text{g2}} = \text{Open}$, $Z_0 = 50\Omega$)

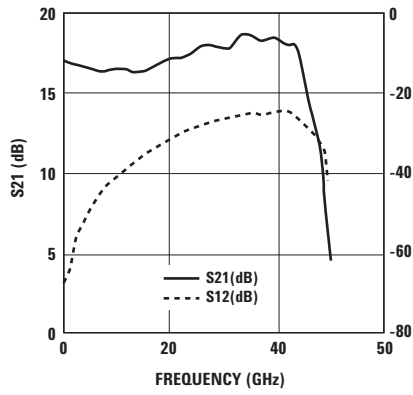


Figure 7. Gain and Reverse Isolation.

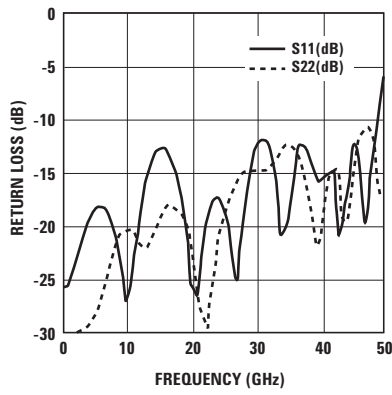


Figure 8. Return Loss (Input and Output).

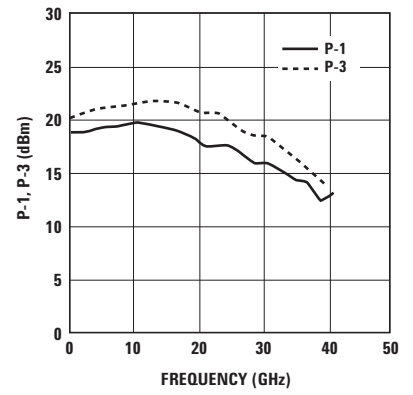


Figure 9. Output Power (P-1 and P-3).

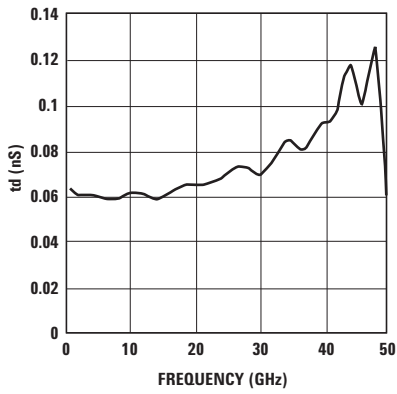


Figure 10. Group Delay.

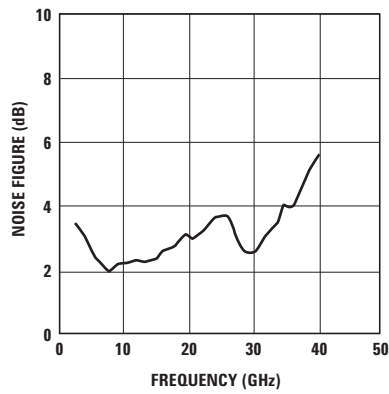


Figure 11. Noise Figure.

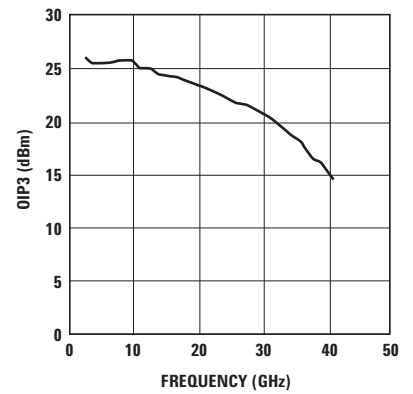


Figure 12. Output IP3.

AMMC-5024 Typical Scattering Parameters^[1] ($T_{\text{chuck}} = 25^{\circ}\text{C}$, $V_{\text{DD}} = 4\text{V}$, $I_{\text{DD}} = 160\text{ mA}$, $Z_{\text{in}} = Z_{\text{out}} = 50\Omega$)

| Freq. GHz | S_{11} | | | S_{21} | | | S_{12} | | | S_{22} | | |
|--------------|----------|-------|----------|----------|-------|----------|----------|-------|----------|----------|-------|----------|
| | dB | Mag | Phase | dB | Mag | Phase | dB | Mag | Phase | dB | Mag | Phase |
| 0.05 | -26.046 | 0.050 | -175.110 | 16.908 | 7.005 | 179.610 | -59.336 | 0.001 | -61.940 | -32.459 | 0.024 | 16.703 |
| 1 | -25.998 | 0.050 | -164.940 | 16.786 | 6.907 | 156.790 | -65.942 | 0.001 | -108.900 | -34.057 | 0.020 | 5.690 |
| 2 | -24.392 | 0.060 | -151.920 | 16.727 | 6.860 | 135.230 | -59.134 | 0.001 | -128.490 | -31.519 | 0.027 | 17.159 |
| 3 | -22.084 | 0.079 | -147.760 | 16.657 | 6.805 | 113.560 | -54.398 | 0.002 | -158.090 | -30.113 | 0.031 | 12.590 |
| 4 | -20.032 | 0.100 | -152.230 | 16.538 | 6.713 | 92.010 | -52.371 | 0.002 | -178.300 | -29.546 | 0.033 | 10.367 |
| 5 | -18.871 | 0.114 | -160.550 | 16.419 | 6.621 | 70.825 | -49.621 | 0.003 | 161.460 | -28.527 | 0.037 | 9.842 |
| 6 | -18.430 | 0.120 | -170.290 | 16.305 | 6.535 | 49.938 | -47.520 | 0.004 | 141.190 | -26.705 | 0.046 | 8.417 |
| 7 | -18.727 | 0.116 | 179.750 | 16.225 | 6.475 | 29.369 | -45.659 | 0.005 | 119.280 | -24.546 | 0.059 | -0.474 |
| 8 | -19.934 | 0.101 | 170.600 | 16.227 | 6.476 | 8.799 | -43.865 | 0.006 | 97.498 | -22.558 | 0.074 | -17.521 |
| 9 | -22.656 | 0.074 | 164.210 | 16.287 | 6.522 | -12.033 | -42.482 | 0.008 | 74.972 | -21.031 | 0.089 | -41.715 |
| 10 | -27.478 | 0.042 | -179.640 | 16.384 | 6.595 | -33.532 | -41.201 | 0.009 | 53.471 | -20.499 | 0.094 | -72.840 |
| 11 | -25.347 | 0.054 | -126.840 | 16.410 | 6.614 | -55.435 | -40.162 | 0.010 | 31.594 | -20.801 | 0.091 | -112.770 |
| 12 | -19.749 | 0.103 | -120.480 | 16.336 | 6.559 | -77.463 | -39.239 | 0.011 | 10.910 | -21.844 | 0.081 | -161.860 |
| 13 | -16.206 | 0.155 | -131.310 | 16.209 | 6.464 | -98.816 | -38.327 | 0.012 | -9.819 | -22.131 | 0.078 | 138.490 |
| 14 | -14.011 | 0.199 | -146.840 | 16.158 | 6.425 | -119.500 | -37.323 | 0.014 | -29.734 | -20.818 | 0.091 | 82.104 |
| 15 | -12.962 | 0.225 | -164.520 | 16.210 | 6.464 | -140.230 | -36.407 | 0.015 | -50.251 | -19.513 | 0.106 | 36.945 |
| 16 | -12.935 | 0.226 | 176.980 | 16.352 | 6.570 | -161.440 | -35.276 | 0.017 | -72.076 | -18.421 | 0.120 | -0.979 |
| 17 | -13.689 | 0.207 | 159.730 | 16.530 | 6.707 | 176.800 | -34.270 | 0.019 | -94.562 | -18.158 | 0.124 | -34.038 |
| 18 | -15.570 | 0.167 | 143.690 | 16.717 | 6.853 | 154.440 | -33.419 | 0.021 | -118.010 | -18.744 | 0.116 | -67.232 |
| 19 | -19.085 | 0.111 | 128.620 | 16.846 | 6.955 | 131.460 | -32.607 | 0.023 | -141.710 | -20.205 | 0.098 | -96.759 |
| 20 | -25.363 | 0.054 | 133.080 | 16.926 | 7.020 | 108.520 | -31.889 | 0.025 | -166.020 | -23.130 | 0.070 | -128.700 |
| 21 | -26.442 | 0.048 | -165.970 | 16.965 | 7.051 | 85.461 | -31.268 | 0.027 | 169.730 | -27.569 | 0.042 | -173.310 |
| 22 | -20.900 | 0.090 | -156.420 | 17.054 | 7.124 | 62.568 | -30.682 | 0.029 | 145.660 | -33.534 | 0.021 | 98.102 |
| 23 | -18.349 | 0.121 | -172.490 | 17.170 | 7.220 | 39.543 | -30.022 | 0.032 | 121.250 | -26.084 | 0.050 | 10.942 |
| 24 | -17.560 | 0.132 | 168.580 | 17.320 | 7.345 | 16.078 | -29.439 | 0.034 | 96.409 | -21.809 | 0.081 | -29.430 |
| 25 | -18.343 | 0.121 | 145.730 | 17.534 | 7.528 | -8.082 | -28.885 | 0.036 | 70.972 | -18.685 | 0.116 | -66.154 |
| 26 | -20.831 | 0.091 | 110.490 | 17.708 | 7.680 | -32.996 | -28.374 | 0.038 | 44.076 | -16.869 | 0.143 | -100.080 |
| 27 | -25.482 | 0.053 | 47.234 | 17.813 | 7.774 | -58.575 | -27.893 | 0.040 | 17.025 | -15.693 | 0.164 | -136.500 |
| 28 | -21.019 | 0.089 | -43.397 | 17.786 | 7.750 | -84.438 | -27.722 | 0.041 | -10.669 | -15.062 | 0.177 | -174.690 |
| 29 | -15.842 | 0.161 | -84.248 | 17.674 | 7.651 | -110.030 | -27.501 | 0.042 | -38.170 | -15.047 | 0.177 | 144.500 |
| 30 | -13.096 | 0.221 | -115.690 | 17.547 | 7.540 | -134.660 | -27.408 | 0.043 | -65.246 | -15.045 | 0.177 | 101.700 |
| 31 | -11.817 | 0.257 | -144.730 | 17.670 | 7.648 | -159.020 | -27.130 | 0.044 | -92.100 | -14.911 | 0.180 | 56.891 |
| 32 | -12.588 | 0.235 | -171.610 | 17.969 | 7.915 | 175.550 | -26.768 | 0.046 | -119.520 | -14.657 | 0.185 | 6.430 |
| 33 | -14.900 | 0.180 | 163.390 | 18.362 | 8.282 | 148.060 | -26.185 | 0.049 | -148.970 | -13.556 | 0.210 | -42.887 |
| 34 | -21.159 | 0.088 | 161.170 | 18.588 | 8.500 | 118.310 | -25.723 | 0.052 | 179.060 | -12.691 | 0.232 | -92.108 |
| 35 | -20.309 | 0.097 | -141.280 | 18.465 | 8.380 | 88.090 | -25.559 | 0.053 | 145.960 | -12.218 | 0.245 | -138.540 |
| 36 | -14.744 | 0.183 | -158.220 | 18.201 | 8.130 | 59.059 | -25.633 | 0.052 | 113.580 | -13.056 | 0.222 | -178.190 |
| 37 | -12.538 | 0.236 | 170.230 | 18.066 | 8.004 | 30.963 | -25.760 | 0.052 | 82.862 | -14.378 | 0.191 | 143.400 |
| 38 | -13.339 | 0.215 | 132.480 | 18.167 | 8.098 | 1.607 | -25.749 | 0.052 | 52.499 | -16.970 | 0.142 | 116.660 |
| 39 | -15.011 | 0.178 | 78.005 | 18.276 | 8.200 | -29.543 | -25.454 | 0.053 | 20.356 | -21.811 | 0.081 | 111.200 |
| 40 | -16.105 | 0.157 | 6.891 | 18.189 | 8.118 | -62.709 | -25.424 | 0.054 | -13.439 | -20.840 | 0.091 | 134.530 |
| 41 | -14.757 | 0.183 | -61.000 | 17.917 | 7.868 | -95.764 | -25.415 | 0.054 | -47.607 | -16.035 | 0.158 | 118.260 |
| 42 | -15.383 | 0.170 | -108.170 | 17.784 | 7.748 | -128.890 | -25.467 | 0.053 | -83.226 | -15.120 | 0.175 | 80.564 |
| 43 | -21.471 | 0.084 | -141.240 | 17.922 | 7.872 | -165.490 | -25.277 | 0.054 | -122.260 | -16.069 | 0.157 | 25.234 |
| 44 | -18.182 | 0.123 | -72.748 | 17.442 | 7.449 | 151.790 | -25.857 | 0.051 | -166.580 | -19.776 | 0.103 | -75.636 |
| 45 | -12.590 | 0.235 | -105.520 | 15.750 | 6.130 | 110.450 | -27.536 | 0.042 | 150.440 | -14.233 | 0.194 | -173.290 |
| 46 | -13.269 | 0.217 | -153.320 | 13.940 | 4.978 | 75.442 | -29.470 | 0.034 | 112.520 | -11.523 | 0.265 | 139.690 |
| 47 | -20.284 | 0.097 | 126.900 | 12.983 | 4.458 | 40.022 | -30.994 | 0.028 | 73.538 | -10.251 | 0.307 | 102.000 |
| 48 | -14.029 | 0.199 | -5.310 | 11.793 | 3.887 | -5.741 | -33.295 | 0.022 | 27.040 | -12.501 | 0.237 | 75.692 |
| 49 | -9.656 | 0.329 | -41.069 | 7.696 | 2.426 | -50.048 | -39.913 | 0.010 | -10.430 | -17.076 | 0.140 | 74.549 |
| 50 | -5.683 | 0.520 | -68.263 | 4.495 | 1.678 | -69.558 | -44.196 | 0.006 | 11.969 | -12.434 | 0.239 | 98.012 |

Note:

1. Data obtained from on-wafer measurements.

AMMC-5024 Typical Performance (Over Temperature and Voltage)

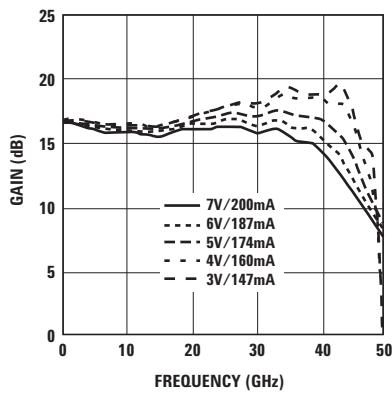


Figure 13. Gain and Voltage.

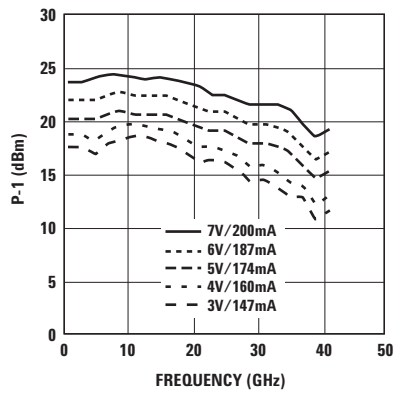


Figure 14. P-1 and Voltage.

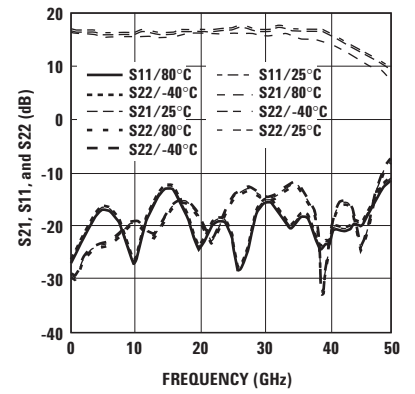


Figure 15. Gain and Return Loss with Temperature.

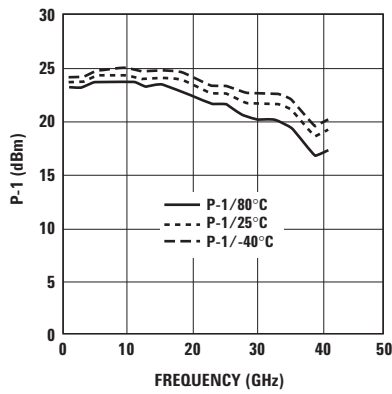


Figure 16. P-1 and Temperature, $V_{dd}=7V$, $I_{dd}=200$ mA.

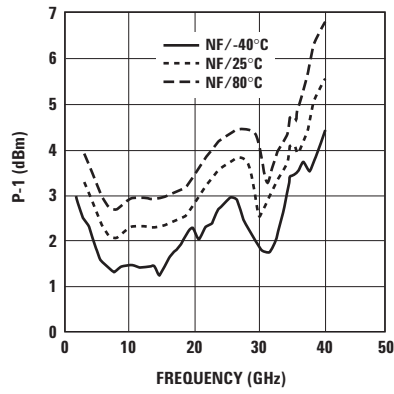


Figure 17. Noise Figure and Temperature at $V_{dd}=4V$, $I_{dd}=160$ mA.

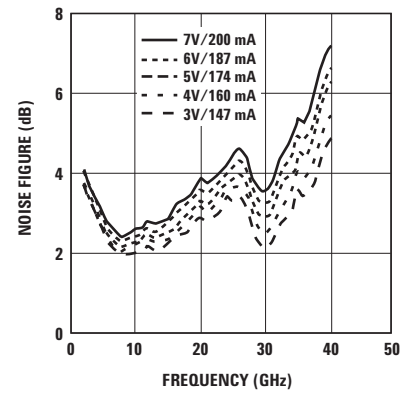


Figure 18. Noise Figure and Voltage.

Biasing and Operation

AMMC-5024 is biased with a single positive drain supply (V_{dd}) a negative gate supply (V_{g1}) and has a positive control gate supply (V_{g2}).

For best overall performance the recommended bias condition for the AMMC-5024 is $V_{dd} = 7V$ and $I_{dd} = 200$ mA. To achieve this drain current level, V_{g1} is typically between -2.5 to $-3.5V$. Typically, DC current flow for V_{g1} is -10 mA. Open circuit is the default setting for V_{g2} when not utilizing gain control.

Using the simplest form of assembly (Figure 20), the device is capable of delivering flat gain over a 2–50 GHz range with a minimum of gain slope and ripple. However, this device is designed with DC coupled RF I/O ports, and operation may be extended to lower frequencies (<2 GHz) through the use of off-chip low-frequency extension circuitry and proper external biasing components. With low frequency bias extension it may be used in a variety of time-domain applications (through 40 Gb/s).

Figure 21 shows a typical assembly configuration.

When bypass capacitors are connected to the AUX pads, the low frequency limit is extended down to the corner frequency determined by the bypass capacitor and the combination of the on-chip 50 ohm load and small de-queing resistor. At this frequency the small signal gain will increase in magnitude and stay at this elevated level down to the point where the C_{aux} bypass capacitor acts as an open circuit, effectively rolling off the gain completely. The low frequency

limit can be approximated from the following equation:

$$f_{C_{aux}} = \frac{1}{2\pi C_{aux}(R_o + R_{DEQ})}$$

where:

R_o is the 50Ω gate or drain line termination resistor.

R_{DEQ} is the small series de-queing resistor and 10Ω.

C_{aux} is the capacitance of the bypass capacitor connected to the AUX Drain and AUX Gate pad in farads.

With the external bypass capacitors connected to the AUX gate and AUX drain pads, gain will show a slight increase between 1.0 and 1.5 GHz. This is due to a series combination of C_{aux} and the on chip resistance but is exaggerated by the parasitic inductance (L_c) of the bypass capacitor and the inductance of the bond wire (L_d). Therefore the bond wire from the Aux pads to the bypass capacitors should be made as short as possible.

Input and output RF ports are DC coupled; therefore, DC decoupling capacitors are required if there are DC paths. (Do not attempt to apply bias to these pads.)

RF bond connections should be kept as short as possible to reduce RF lead inductance which will degrade performance above 20 GHz.

An optional output power detector network is also provided. Detector sensitivity is optimized by biasing the diodes with typical drain voltage $V_{dd} = 7$ volts. Simply connecting Det-Bias to the V_{dd} supply is a convenient method of biasing this detector network. The

differential voltage between the Det-Ref and Det-Out pads can be correlated with the RF power emerging from the RF output port. A >0.5 μF capacitor is required for the Det_Out pad to expand power detection performance below 100 MHz.

Ground connections are made with plated through-holes to the backside of the device; therefore, ground wires are not needed.

Assembly Techniques

The chip should be attached directly to the ground plane using either a fluxless AuSn solder preform or electrically conductive epoxy^[1]. For conductive epoxy, the amount should be just enough to provide a thin fillet around the bottom perimeter of the die. The ground plane should be free of any residue that may jeopardize electrical or mechanical attachment. Caution should be taken to not exceed the Absolute Maximum Rating for assembly temperature and time.

Thermosonic wedge bonding is the preferred method for wire attachment to the bond pads. The RF connections should be kept as short as possible to minimize inductance. Gold mesh^[2] or double-bonding with 0.7 mil gold wire is recommended.

Mesh can be attached using a 2 mil round tracking tool and a tool force of approximately 22 grams with an ultrasonic power of roughly 55 dB for a duration of 76 ± 8 mS. A guided wedge at an ultrasonic power level of 64 dB can be used for the 0.7 mil wire. The recommended wire bond stage temperature is $150 \pm 2^\circ C$.

The chip is 100 μm thick and should be handled with care.

This MMIC has exposed air bridges on the top surface. Handle at edges or with a custom collet (do not pick up die with vacuum on die center.)

This MMIC is also static sensitive and ESD handling precautions should be taken.

For more detailed information, see Agilent Application Note 54 “GaAs MMIC ESD, Die Attach and Bonding Guidelines.”

Notes:

1. Ablebond 84-1 LM1 silver epoxy is recommended.
2. Buckbee-Mears Corporation, St. Paul, MN, 800-262-3824

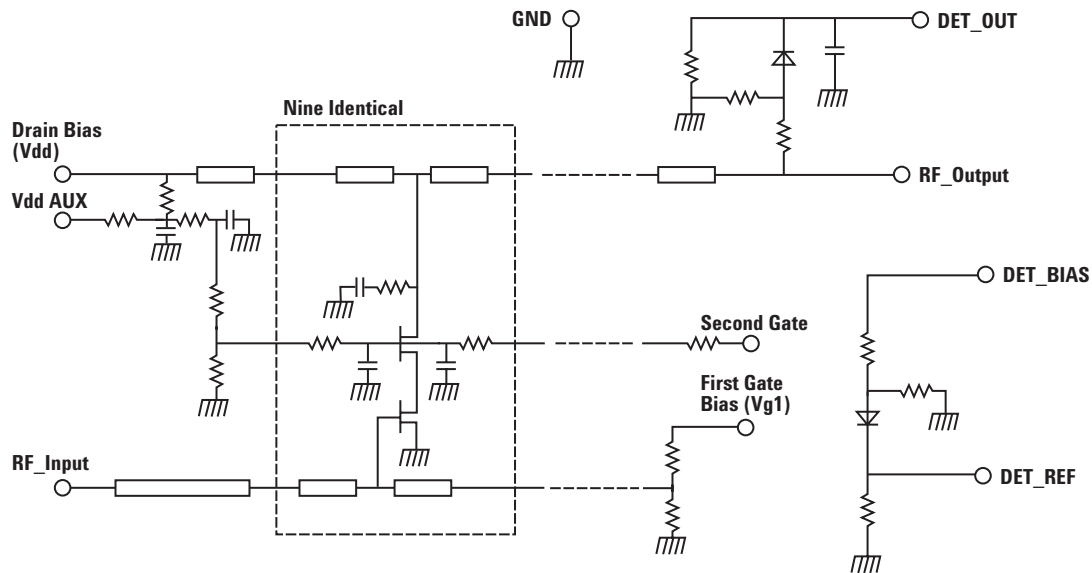


Figure 19. AMMC-5024 Schematic.

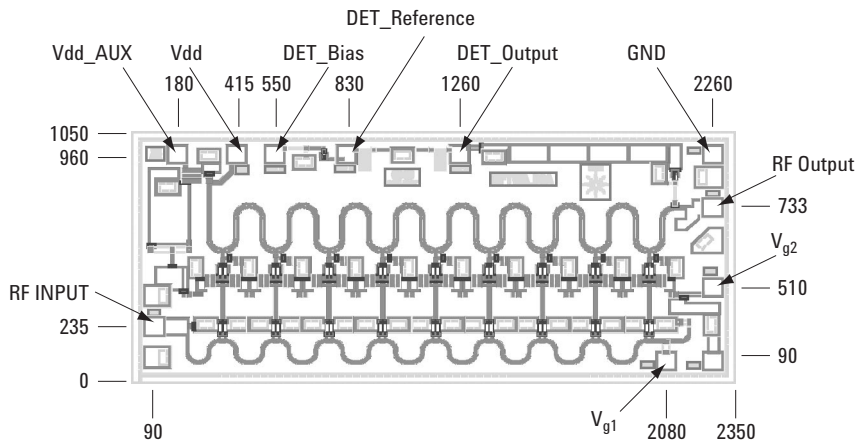


Figure 20. AMMC-5024 Bonding Pad Locations. (dimensions in micrometers)

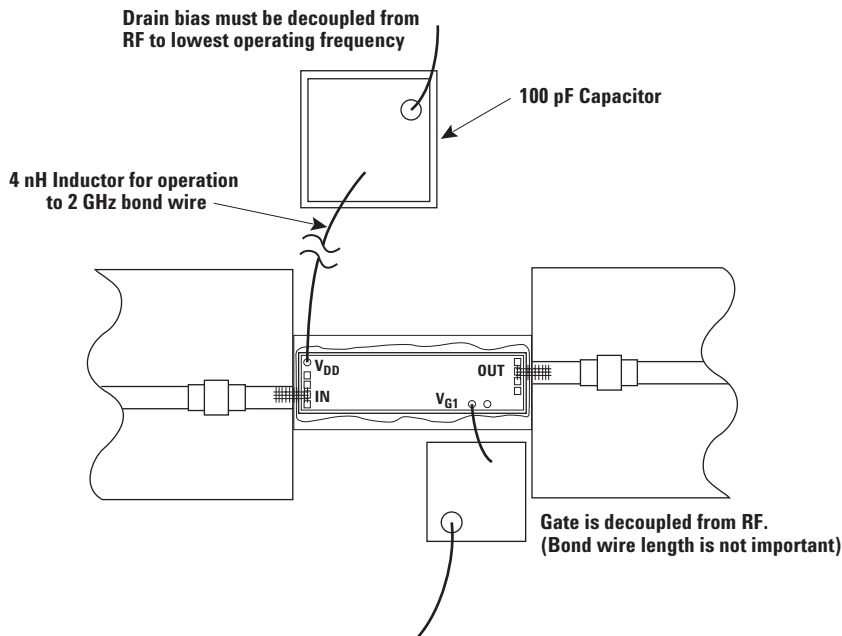


Figure 21. AMMC-5024 Assembly Diagram.

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August 5, 2003

5988-9884EN



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